

FORM PTO-1449		U. S DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO.		SERIAL NO.		
				U 015850-2		10/542,123		
INFORMATION DISCLOSURE STATEMENT BY APPLICANT  (Use several sheets if necessary)		APPLICANT						
		Vladimir Pavlovich POPOV et al.						
		FILING DATE			GROUP			
		December 9, 2005			2812			
U.S. PATENT DOCUMENTS								
EXAMINER INITIALS	REFERENCE DESIGNATION	DOCUMENT NUMBER	DATE	NAME		FILING DATE IF APPROPRIATE		
	AA							
	AB							
	AC							
FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY		TRANSLATION		
						YES	NO	
	AD							
	AE							
	AF							
OTHER ART (Including Author, Title, Date, Pertinent Dates, Etc.)								
/QJ/	AG	Rieutord, F. et al. "Dynamics of a Bonding Front" <i>Physical Review Letters</i> (2005) PRL Vol. 94						
/QJ/	AH	Takahagi, T. et al. "Adsorbed Water on a Silicon Wafer Surface Exposed to Atmosphere" <i>Jpn. J. Appl. Phys.</i> (2001) Vol. 40, No. 11, Part 1, pp 6198-6201						
/QJ/	AI	Gosele, U. et al. "Self-Propagating Room-Temperature Silicon Wafer Bonding in Ultrahigh Vacuum" <i>Appl. Phys. Lett.</i> (1995) Vol. 67, No. 24, pp 3614-3616						
/QJ/	AJ	Farrens, S.N. et al. "Chemical Free Room Temperature Wafer to Wafer Direct Bonding" <i>J. Electrochem. Soc.</i> (1995) Vol. 142, No. 11, pp 3949-3955						
/QJ/	AK	Tong, Q. Y. et al. "Low Vacuum Wafer Bonding" <i>Electrochemical and Solid-State Letters</i> (1998) Vol. 1, No. 1, pp 52-53						
/QJ/	AL	Tong, Q. Y. et al. "Semiconductor Wafer Bonding: Science and Technology" <i>John Wiley &amp; Sons, Inc.</i> (1999) pp 52-53, and pp 122-127						
/QJ/	AM	Esser, R. H. et al. "Improved Low-Temperature Si-Si Hydrophilic Wafer Bonding" <i>Journal of the Electrochemical Society</i> (2003) Vol. 150, No. 3, G228-G231						
/QJ/	AN	Dragoi, V. et al. "Plasma Activated Wafer Bonding for MEMS" <i>SPIE Proceeding</i> 5836 (2005) paper no. 5836-19						
/QJ/	AO	"Long-Term Stability of Vacuum-Encapsulated MEMS Devices Using Eutectic Wafer Bonding" <i>VABOND-Deliverable 6.4 - Technology Guidelines on Vacuum Encapsulation of MEMS</i>						
/QJ/	AP	Zhang, X. et al. "Low-Temperature Wafer Bonding Optimal O <sub>2</sub> Plasma Surface Pretreatment Time" <i>Electrochemical and Solid-State Letters</i> (2004) Vol. 7, No. 8, G172-G174						
EXAMINER		/Quovaunda Jefferson/			DATE CONSIDERED			06/19/2007
EXAMINER:		Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.						